

GET- 30497

Qualification Test Results  
on Si MMIC (use NESAT3 Process)

*uPC 2710P*

Prepared on : September 8, 1994

Prepared by : *T. Kato*  
Taizo Kato  
Engineer

*Y. Emura*  
Yoichi Emura  
Assistant Manager

Approved by : *M. Matsuo*  
Masanori Matsuo  
Engineering Manager  
Reliability & QC Department  
Compound Semiconductor Devices  
Division  
IC & Discrete Operation Unit  
NEC Corporation

## 1. Introduction

In the fields of communication systems and consumer electronics (e.g. CATV receivers, SHF broadcasting receivers and BS/CS tuners), analog and digital ICs from UHF to microwave frequency range are widely used. These analog and digital ICs are required for compactness, economy and high reliability.

To respond to above described requirement, NEC has developed many kinds of Si-monolithic microwave ICs.

In this report, the device structure and the results of the reliability qualification tests on Si MMICs are described.

Qualification tests have been performed for the MMIC and the MMIC elements such as transistor, resistor and capacitor.

## 2. Device structure

Fig.1 ~Fig.3 show the cross sectional view of transistor cell, capacitor and resistor. The MNS (Metal Nitride Semiconductor) structure is adopted in capacitors.

The resistors are formed by polysilicon.

The features of transistor cell are described below:

- (1) An optimal epitaxial layer grown by VPE (Vapour Phased Epitaxy).
- (2) Oxide isolation to reduce parasitic capacitance.
- (3) A shallow and higher impurity doped base by ion implantation.

A shallow emitter by diffusion from As-doped polysilicon.

- (4) An emitter of  $0.5\mu\text{m}$  width processed by photo lithograph.
- (5) A nitride passivation film.
- (6) A Ti-Pt-Au electrode structure.

### 3. Qualification Tests

#### (1) Qualification Tests on Basic Element.

Design rules for ICs are qualified by performing qualification test on each basic elements consisting of IC such as transistor, capacitor and resistor.

A series of qualification tests on basic elements consist of following items:

- (a) High temperature storage tests at  $T_a=259^{\circ}\text{C}$ ,  $295^{\circ}\text{C}$  and  $337^{\circ}\text{C}$  on transistor and resistor.
- (b) High temperature DC bias test at  $T_j=200^{\circ}\text{C}$  on capacitor.

#### (2) Qualification Tests on IC

Qualification tests of ICs are performed on typical types of each family classified by integration level, function, structure and production technique applied.

A series of qualification tests on IC consist of following items:

- (a) Environmental tests (Thermal and Mechanical).
- (b) Radiation hardness.
- (c) Solderability strength.
- (d) High temperature storage tests at  $T_a=200^{\circ}\text{C}$ .
- (e) High temperature DC bias tests at  $T_j=200^{\circ}\text{C}$ .

Test conditions and sample size of the qualification tests are shown Table 1.

The delta parameters and criteria are shown in Table 2-1 and Table 2-2.

#### 4. Test results and Discussions

Basic element
---------------

##### (1) Transistor

The summary of qualification test results are presented at Table 3.

###### High temperature storage test

High temperature storage test at  $T_a=259^\circ\text{C}$ ,  $295^\circ\text{C}$  and  $337^\circ\text{C}$  were performed using 10 samples. The test results are shown Table 4.

At the high temperature stress level ( $T_a=337^\circ\text{C}$ ), the samples have started to fail from 100 hours. The failure mode is  $h_{FE}$  degradation. This is caused by diffusion of Au into Si due to degradation of Pt as barrier metallization.

The Arrhenius plots on the tests are shown in Fig.4, using  $\Delta E_a=1.8\text{eV}$  that has been confirmed at Au electrode microwave Si transistor.

From this plot, the estimated MTF for transistor at  $T_J=100^\circ\text{C}$  is  $3.0 \times 10^{11}$  hours.

##### (2) Resistor Element

###### Poly silicon Resistor

High temperature storage tests at  $T_a=259^\circ\text{C}$ ,  $295^\circ\text{C}$  and  $337^\circ\text{C}$  were performed using 10 samples for 3000 hours.

The test results are shown Table 5. The Arrhenius plots on the test are shown in Fig. 4. This Arrhenius plot gives the activation energy of 1.8eV. From this plot, the estimated MTF for polysilicon Resistor at  $T_a=100^\circ\text{C}$  is  $3.0 \times 10^{11}$  hours.

##### (3) Capacitor

Biased test on 10 MNS capacitors has been performed with the bias condition of 6V at  $T_a=200^\circ\text{C}$  for 5000 hours.

The test results are shown at Table 6.

No failure was observed.

Consequently, each basic element is considered to be sufficiently reliable for constructing MMICs.

SI MIC
--------

Qualification test have performed for wide-band amplifier IC  $\mu$ PC2710B as the typical type of the family which are classified by process and structure of wafer fabrication.

The equivalent circuit of  $\mu$ PC2710B is shown in Fig. 5.

① High Temperature storage test

High temperature storage test at  $T_a=200^\circ\text{C}$  was performed for  $\mu$ PC2710B using 20 samples.

This test was performed for 3000 hours. The test results are shown Table 7. No failure has been observed for 3000 hours.

② High Temperature DC bias test

High temperature DC bias test at  $T_j=200^\circ\text{C}$  was performed for  $\mu$ PC2710B using 100 samples.

This test was performed for 3000 hours. The test results are shown Table 8. No failure has been observed for 3000 hours.

$\Delta I_{cc}$  and  $\Delta G_p$  changes are shown in Fig. 8.

Any significant variation of the two parameters has not been observed during 3000 hours at  $T_j=200^\circ\text{C}$ .

If one device was failed at the test period of 3000 hours at  $T_j=200^\circ\text{C}$ , the MTF of  $\Delta I_{cc}$  or  $\Delta G_p$  line were drawn in Fig. 7, using  $\Delta E_a=1.8\text{eV}$ , which is confirmed by the results of Au electrode microwave Si transistor. MTF at  $T_j=100^\circ\text{C}$  is estimated to be over  $1 \times 10^8$  hours.

③ Thermal and Mechanical Environmental Test and Solderability Strength.

As shown Table 3, no failure was observed with respect to thermal environmental test, mechanical environmental test and solderability strength.

④ Radiation Hardness

Gamma-ray irradiation test was carried out for wide-band amplifier

IC  $\mu$ PC2710B.

Dose rate is  $1 \times 10^5$  and  $1 \times 10^6$  rad/hour.

The test results are shown Table 3. No failure was observed with respect to this test. Consequently, it was confirmed that the Si MMICs are sufficiently tough from the view point of radiation hardness.

5. Conclusion

Accelerated life test have been performed on wide-band amplifier, their Tr, resistor and capacitor. MTF at  $T_j=100$  °C is estimated to be over  $1 \times 10^6$  hours.

Radiation Hardness tests have been carried out on the wide-band amplifier. No degradation was observed up to  $1 \times 10^6$  rad gamma ray irradiation.

It has confirmed that the Si MMICs are sufficiently reliable for practical applications.

Table 1 Test Item and Test Conditions

Test Item	Test Condition	Sample Size		
		IC	Trasistor	Resistor Capacitor
Environmental Test (Thermal)	a) Soldering Heat 260°C, 10 sec  b) Temperature Cycling -85 °C ~ +25 °C ~ +175°C, 100 Cycles (MIL-STD-883 Method 1010)  c) Thermal Shock 0 °C ~ +100 °C, 100 Cycles (MIL-STD-883 Method 1011)  d) Hermetic Seal Test (MIL-STD-883 Method 1014 Test Condition A <sub>2</sub> and C)	20	-	-
Environmental Test (Mechanical)	a) Shock 1,500G, 0.5ms (MIL-STD-883 Method 2002)  b) Vibration, Variable Frequency 100 ~ 2,000Hz, 20G, 3 axis, 4 min. (MIL-STD-883 Method 2007)  c) Constant Acceleration 20,000G, 3 axis, 1 min. (MIL-STD-883 Method 2001)  d) Hermetic Seal Test (MIL-STD-883 Method 1014 Test Condition A <sub>2</sub> and C)	20	-	-
Radiation Hardness	10 <sup>5</sup> rad by Cobalt 60 10 <sup>6</sup> rad by Cobalt 60 (Non Bias)	5	-	-
Solderability Strength	245 °C, 5 sec (MIL-STD-883 Method 2003)	10	-	-

Test Item and Test Conditions (Continued from Table 1)

Test Item	Test Condition	IC	Sample Size		
			Basic Element		
			Transistor	Resistor	Capacitor
High Temperature Storage Test	a) Ta=200°C	20	—	—	—
	b) Ta=259°C	—	10	—	—
	c) Ta=295°C	—	10	—	—
	d) Ta=337°C	—	10	—	—
	3,000 hours or up to F(t) > 50%				
High Temperature DC Bias Test	a) TJ=175°C	—	—	—	—
	b) IJ=200°C	100	—	—	10



Table 2-1 Delta Parameters and Criteria of Basic Elements

## a) Transistor Element

Parameter	Symbol	Test Condition	Delta Criteria
Collector Cut-off Current	$I_{CBO}$	$V_{CE}=5V$	+100nA or +100% Whichever is greater
Emitter Cut-off Current	$I_{EBO}$	$V_{EB}=1V$	+100nA or +100% Whichever is greater
DC forward Current Gain	$h_{FE}$	$V_{CE}=2.5V$ $I_C=1mA$	$\pm 15\%$

## b) Resistor Element

Parameter	Symbol	Test Condition	Delta Criteria
Resistance	R	$V=0.5V$	$\pm 5\%$

## c) Capacitor Element

Parameter	Symbol	Test Condition	Delta Criteria
Capacitance	C	freq.=1MHz non Bias	$\pm 10\%$

Table 2-2 Delta Parameters and Criteria of Si MMIC

d)  $\mu$ PC2710B

Parameter	Symbol	Test Condition	Delta Criteria
Supply Current	$I_{cc}$	$V_{cc}=5V$ No Signal input	$\pm 15\%$
Power Gain	$G_p$	$V_{cc}=5V$ freq.=0.5GHz	$\pm 1dB$

Table 3 Summary of Qualification Test Results

Test Item	Test Condition	Results (Failure/ Sample)				Reference Figure or Table
		IC	Basic Elements			
			Transistor	Poly Silicon Resistor	Capacitor	
Environmental Test (Thermal)	a) Soldering Heat	0/20	—	—	—	—
	b) Temperature Cycling		—	—	—	
	c) Thermal Shock		—	—	—	
	d) Hermetic Seal Test		—	—	—	
Environmental Test (Mechanical)	a) Shock	0/20	—	—	—	—
	b) Vibration Variable frequency		—	—	—	
	c) Constant Acceleration		—	—	—	
	d) Hermetic Seal Test		—	—	—	
Radiation Hardness	10 <sup>5</sup> rad 10 <sup>6</sup> rad by Cobalt 60	0/5	—	—	—	—
Solderability Strength	a) 245 °C, 5 sec	0/10	—	—	—	—
High Temperature Storage Test	a) Ta=200°C	3000 Hours 0/20	—	—	—	Fig.4 Table 4,5 and 7
	b) Ta=255°C	—	3000 Hours 0/10	3000 Hours 0/10	—	
	c) Ta=295°C	—	3000 Hours 10/10	3000 Hours 7/10	—	
	d) Ta=337°C	—	300 Hours 10/10	1000 Hours 10/10	—	

Summary of Qualification Test Results (Continued from Table 3)

Test Item	Test Condition	Results (Failure/ Sample)				Reference, Figure or Table
		IC	Transistor	Basic Elements Poly Silicon Resistor	Capacitor	
High Temperature DC Bias Test	a) Tj=175°C	—	—	—	—	Fig. 6 and 7 Table 6 and 8
	b) Tj=200°C	3000 Hours 0/100	—	—	5000 Hours 0/10	

Table 4 High Temperature Storage Test of Transistor Element

Test Condition	Quantity	Number of Failures											
		0	50	100	300	500	1000	1500	2000	2500	3000	Hours	
Ta=259 °C	10	0	0	0	0	0	0	0	0	0	0	0	—
Ta=295 °C	10	0	0	0	0	0	3*	6*	8*	9*	10*	—	
Ta=337 °C	10	0	0	4*	10*	—	—	—	—	—	—	—	

\* hFE degradation

Table 5 High Temperature Storage Test of Resistor Element

Poly Silicon Resistor

Test Condition	Quantity	Number of Failures												
		0	10	50	100	300	500	1000	1500	2000	2500	3000	Hours	
Ta=259 °C	10	0	0	0	0	0	0	0	0	0	0	0	0	—
Ta=295 °C	10	0	0	0	0	0	0	1	3	5	5	7	—	
Ta=337 °C	10	0	0	2	5	7	10	—	—	—	—	—	—	

Table 6 High Temperature DC Bias Test of Capacitor

Test Condition	Quantity	Number of Failures						
		0	200	500	1000	3000	5000	Hours
Tj=200 °C	10	0	0	0	0	0	0	—

Table 7 High Temperature Storage Test of SI MMIC

Sample	Quantity	Number of Failures						Hours
		0	168	500	1000	1500	3000	
$\mu$ PC2710B	20	0	0	0	0	0	0	—

Test Condition  $T_a=200^{\circ}\text{C}$



Table 8 High Temperature DC Bias Test of Si MMIC

Sample	Quantity	Number of Failures						Hours
		0	168	500	1000	1500	3000	
μPC2710B	100	0	0	0	0	0	0	—

Test Condition TJ=200°C

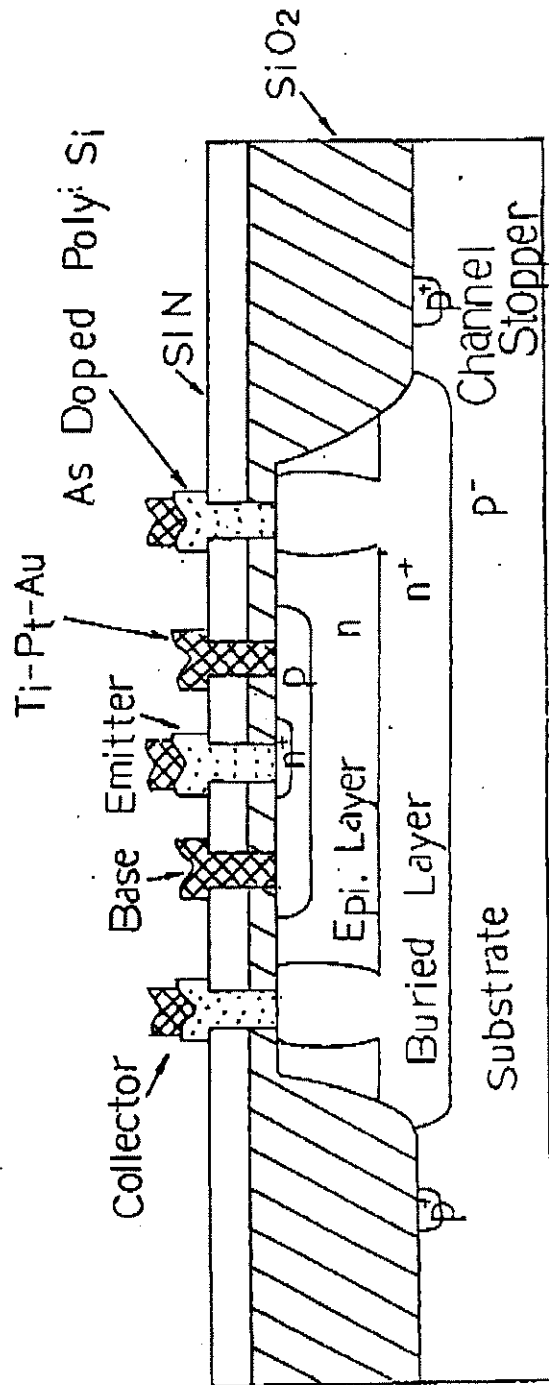


FIG. 1 A TRANSISTOR CROSS SECTIONAL VIEW

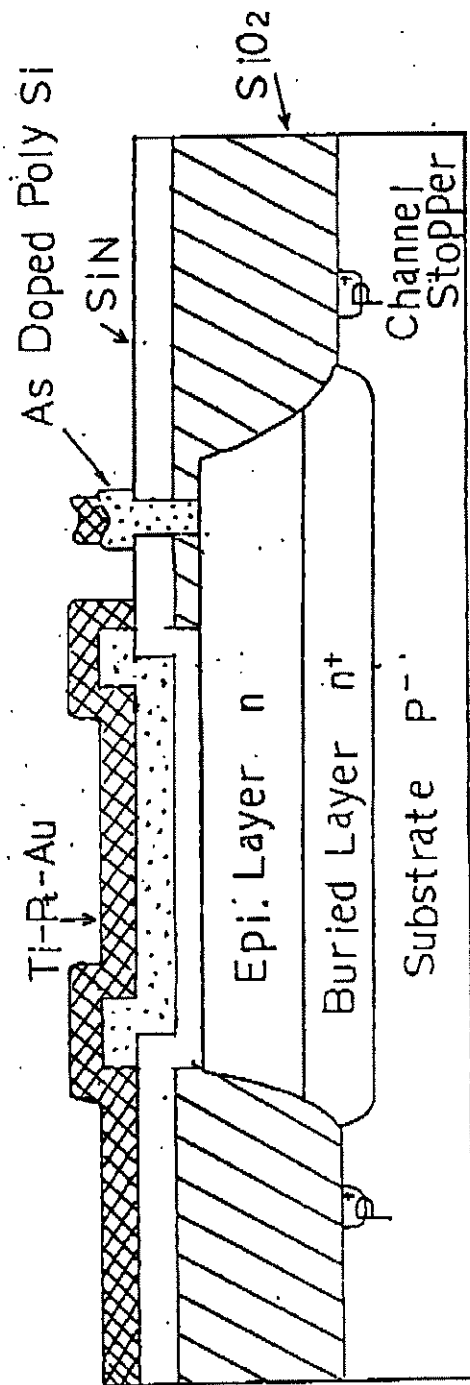


FIG. 2 A CAPACITOR CROSS SECTIONAL VIEW

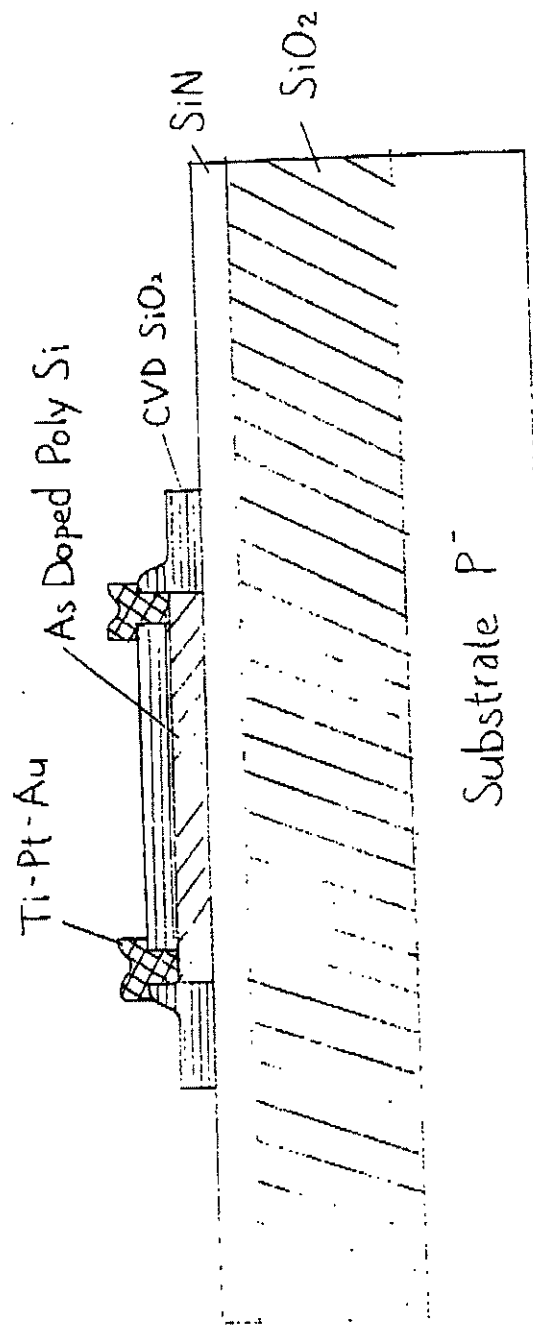
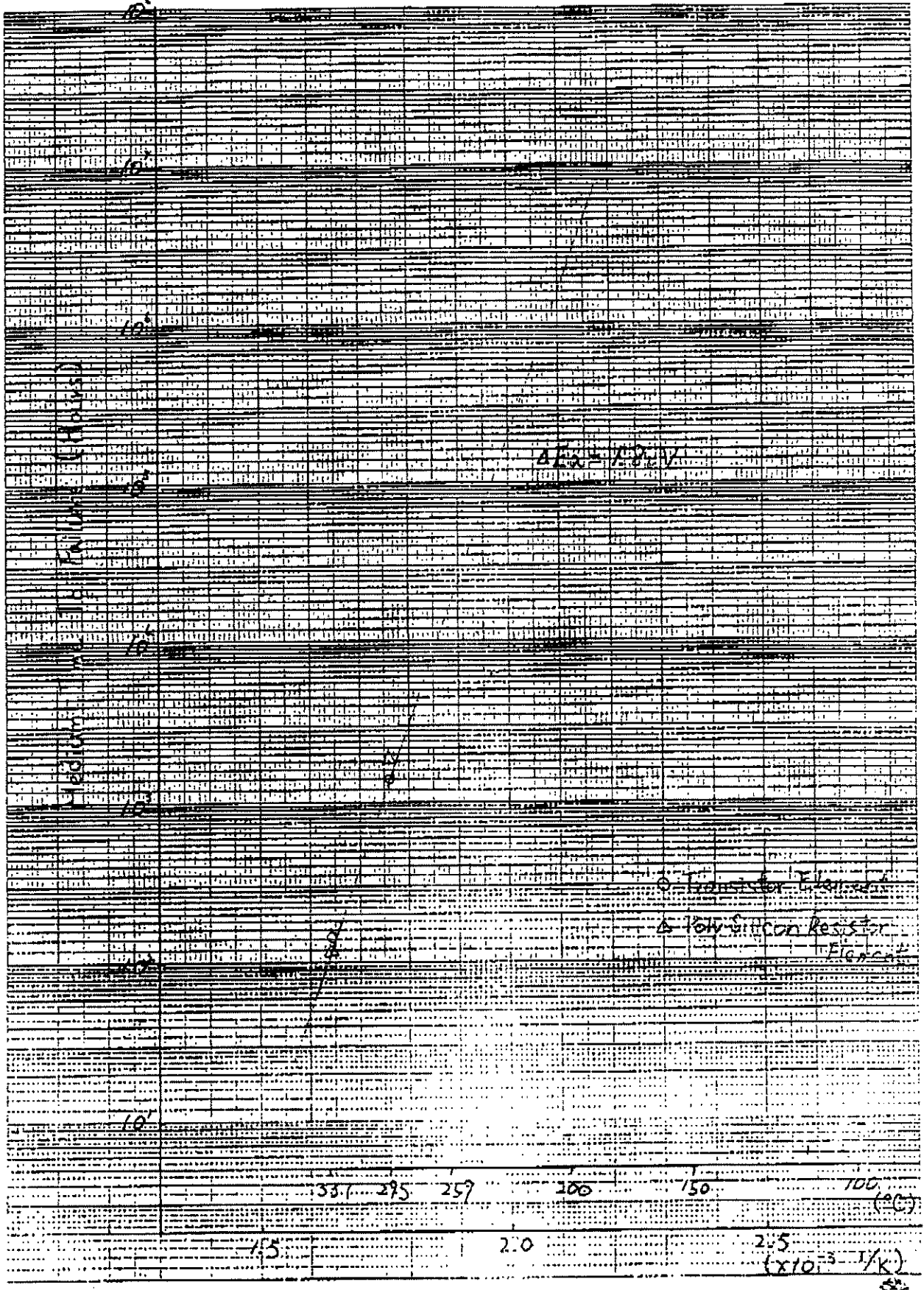


FIG. 3 A RESISTOR CROSS SECTIONAL VIEW

FIG. 4 ARRHENIUS PLOT OF BASIC ELEMENT



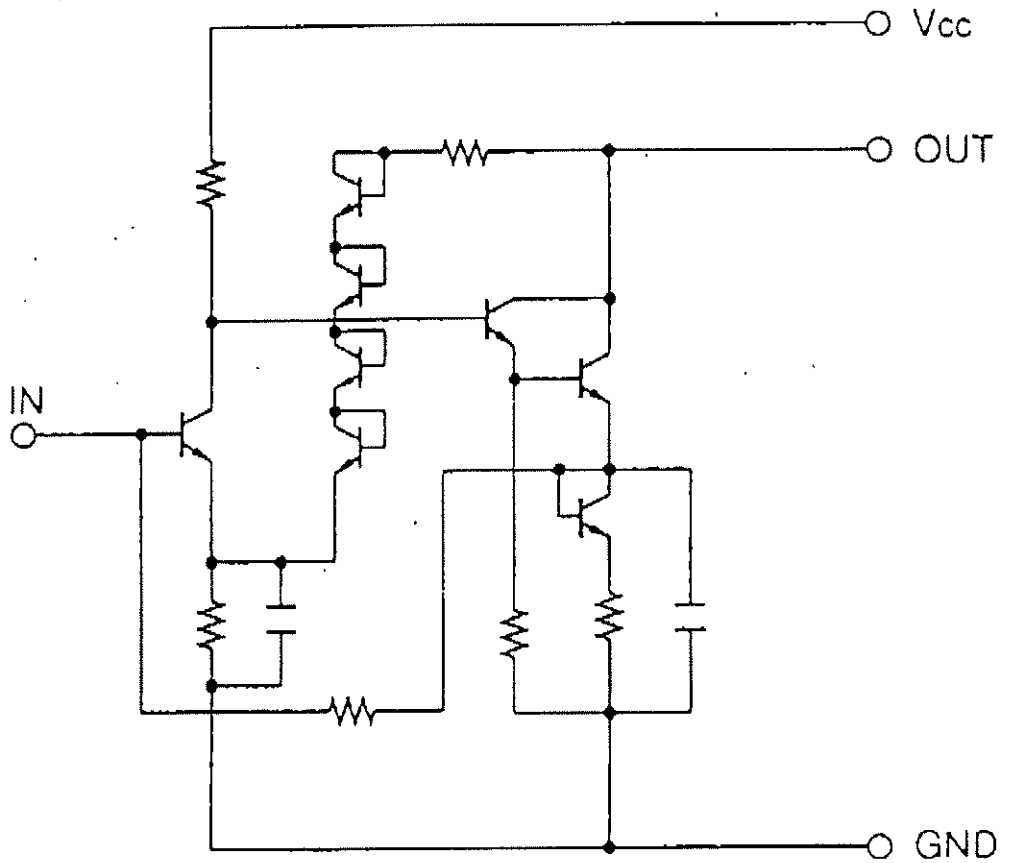


FIG. 5 EQUIVALENT CIRCUIT OF  $\mu\text{PC2710B}$

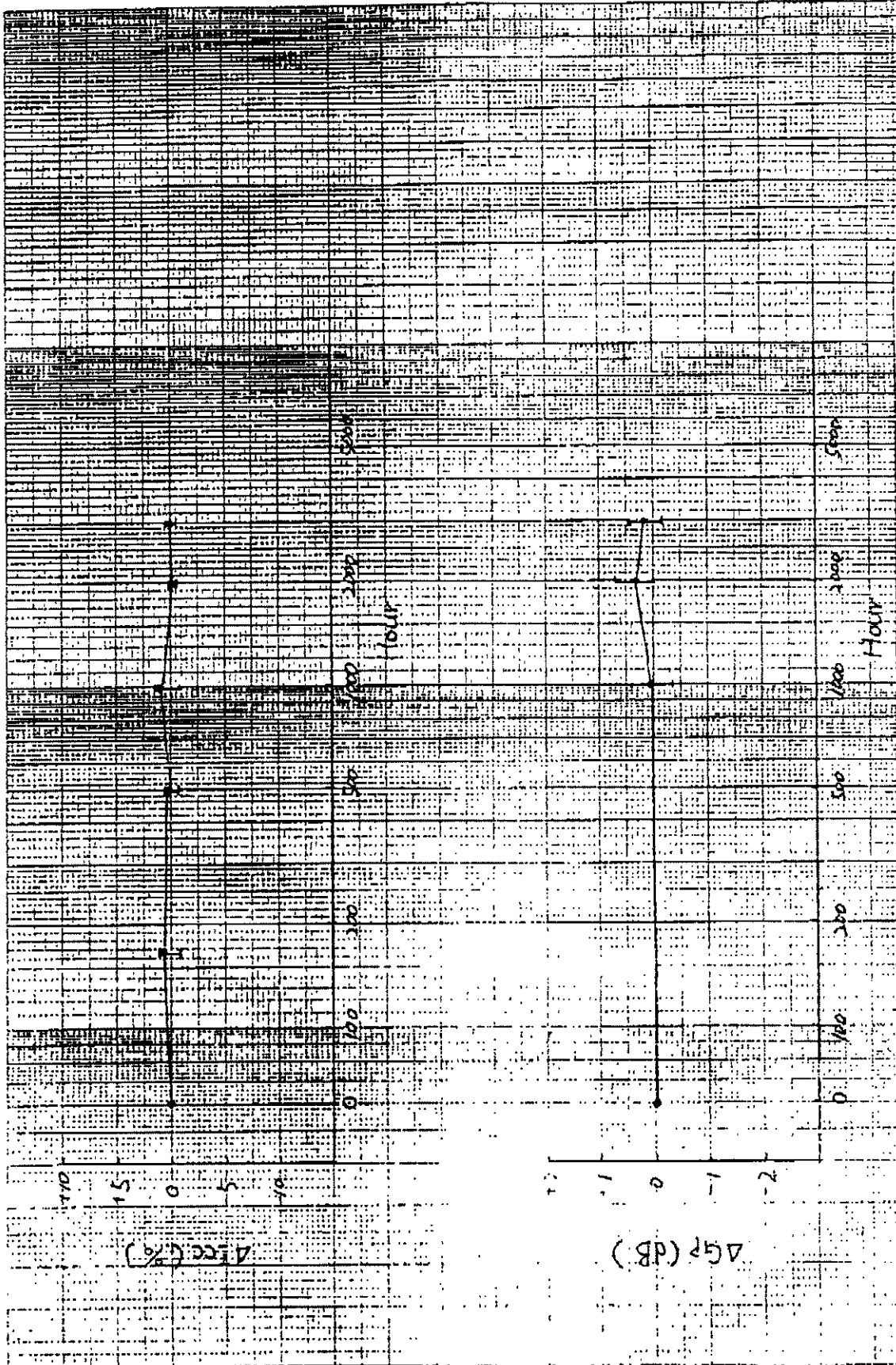


FIG. 6 4PC2710B PARAMETER CHANGES ON HIGH TEMPERATURE DC BIAS TEST

FIG. 7 ARRHNIOUS PLOT OF WIDE BAND AMPLIFIER  
ON HIGH TEMPERATURE DC BIAS TEST

